

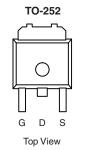
N-Channel 60 V (D-S), 175 °C MOSFET, Logic Level

PRODUCT SUMMARY				
V _{DS} (V)	$r_{DS(on)}(\Omega)$	I _D (A) ^a		
60	0.031 at V _{GS} = 10 V	23		
	0.045 at V _{GS} = 4.5 V	19.5		

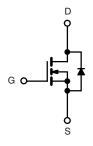
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature





Drain Connected to Tab



N-Channel MOSFET

Ordering Information: SUD23N06-31L SUD23N06-31L-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS $T_C =$	25 °C, unless othe	rwise noted			
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 25 °C	1	23		
	T _C = 100 °C	I _D	16.5		
Pulsed Drain Current		I _{DM}	50	Α	
Continuous Source Current (Diode Conduction)		I _S	23		
Avalanche Current		I _{AS}	20		
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	20	mJ	
Martinus Brown Birelantin	T _C = 25 °C	В	100	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	3 ^a		
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	R _{thJA}	18	22	°C/W
Maximum Junction-to-Ambient	Steady State	' 'thJA	40	50	
Maximum Junction-to-Case		R _{thJC}	3.2	4	

a. Surface Mounted on 1" x 1" FR4 board, $t \le 10$ sec.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

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SPECIFICATIONS $T_J = 25$ Parameter	Symbol	Test Conditions	Min	Typ ^a	Max	Unit	
Static	- Cynnoon	Tool Containons		קעי	Mux	J.III	
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$ $V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$ 60						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.0	2.0	3.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	400	V _{DS} = 60 V, V _{GS} = 0 V			1	μΑ	
	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C			50		
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	50			Α	
		V _{GS} = 10 V, I _D = 15 A		0.025	0.031		
h		V _{GS} = 10 V, I _D = 15 A, T _J = 125 °C			0.055	Ω	
Drain-Source On-State Resistance ^b	r _{DS(on)}	V _{GS} = 10 V, I _D = 15 A, T _J = 175 °C			0.069		
		V _{GS} = 4.5 V, I _D = 10 A		0.037	0.045		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		20		S	
Dynamic ^a	•			•			
Input Capacitance	C _{iss}			670		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		140			
Reverse Transfer Capacitance	C _{rss}			60			
Total Gate Charge ^c	Qg			11	17	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 23 \text{ A}$		3			
Gate-Drain Charge ^c	Q _{gd}			3			
Turn-On Delay Time ^c	t _{d(on)}			8	15	ns	
Rise Time ^c	t _r	V_{DD} = 30 V, R_L = 1.3 Ω I_D \cong 23 A, V_{GEN} = 10 V, R_g = 2.5 Ω		15	25		
Turn-Off Delay Time ^c	t _{d(off)}			30	45		
Fall Time ^c	t _f			25	40		
Source-Drain Diode Ratings and Cha	aracteristics	(T _C = 25 °C)		_			
Pulsed Current	I _{SM}				50	Α	
Diode Forward Voltage	V_{SD}	$I_F = 15 \text{ A}, V_{GS} = 0 \text{ V}$		1.0	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 15 A, di/dt = 100 A/μs		30	60	ns	

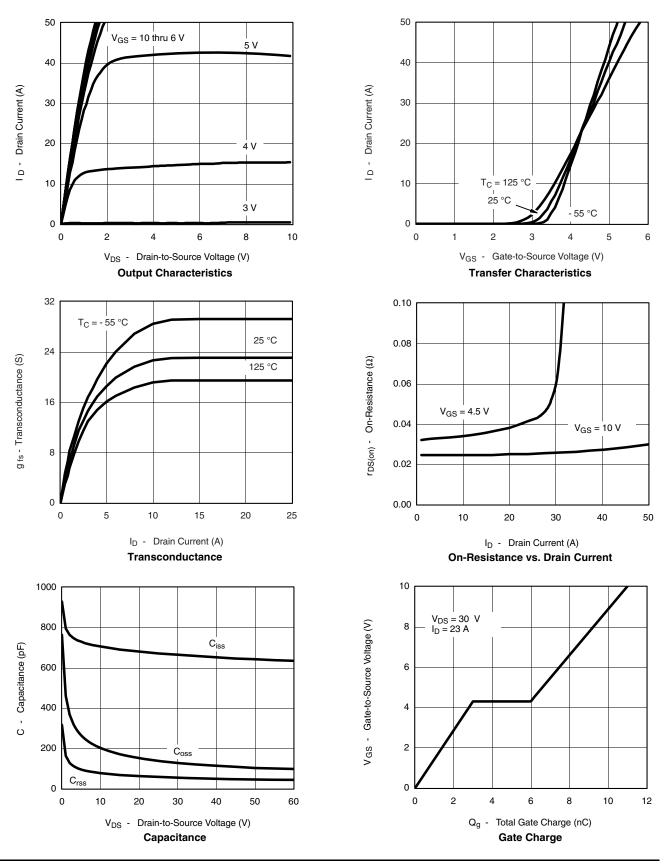
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



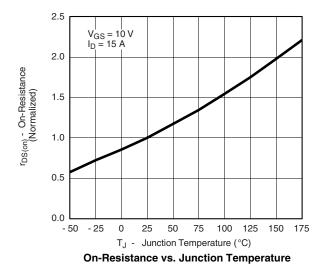
TYPICAL CHARACTERISTICS 25 °C unless noted

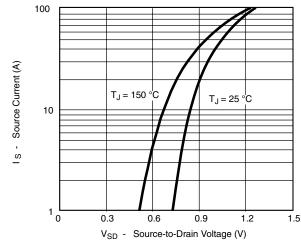


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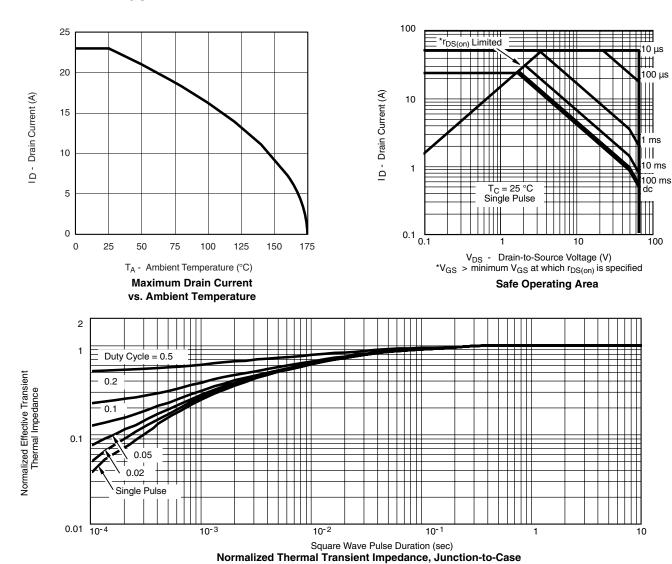




Source-Drain Diode Forward Voltage



THERMAL RATINGS



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72145.



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